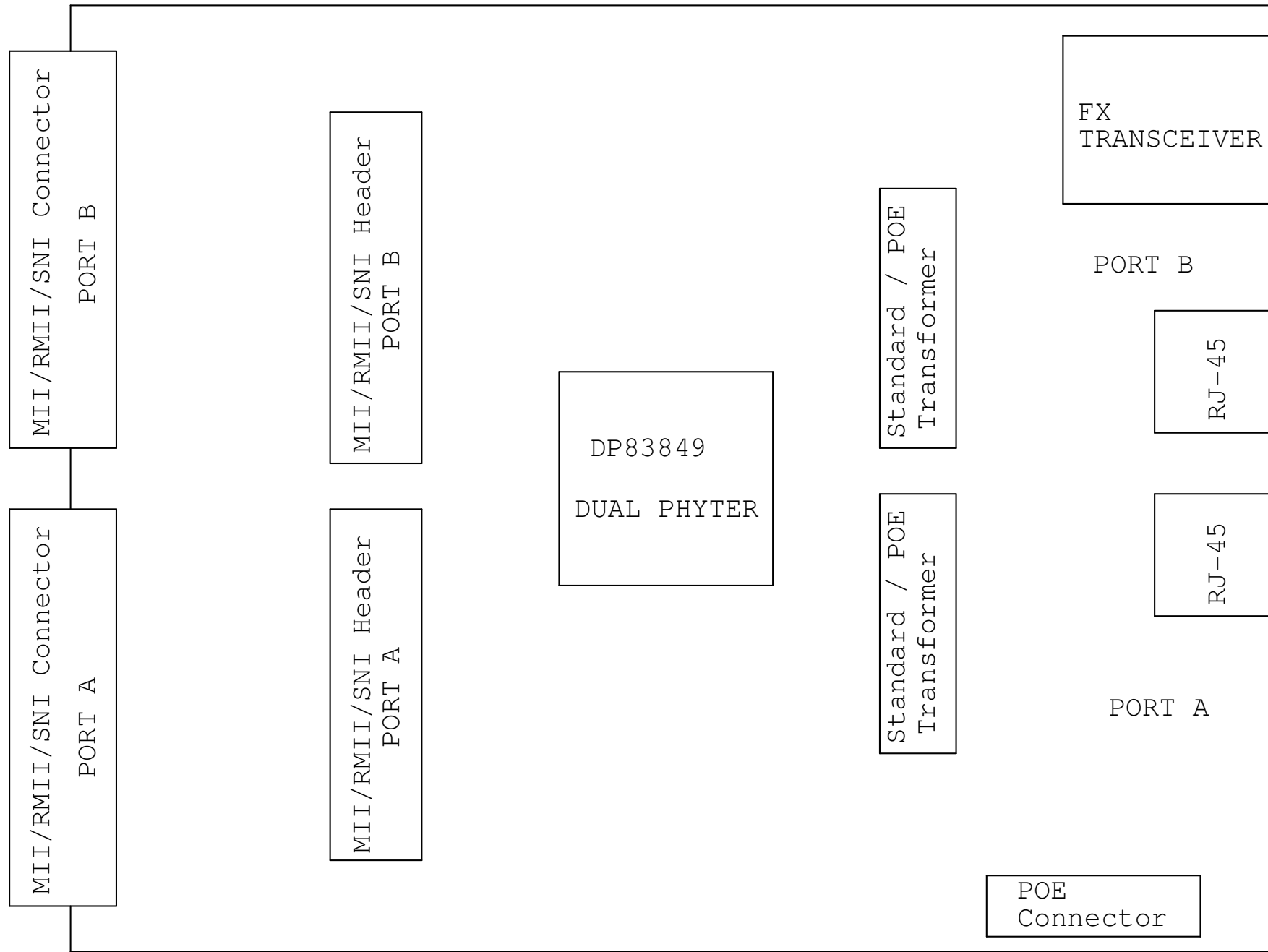


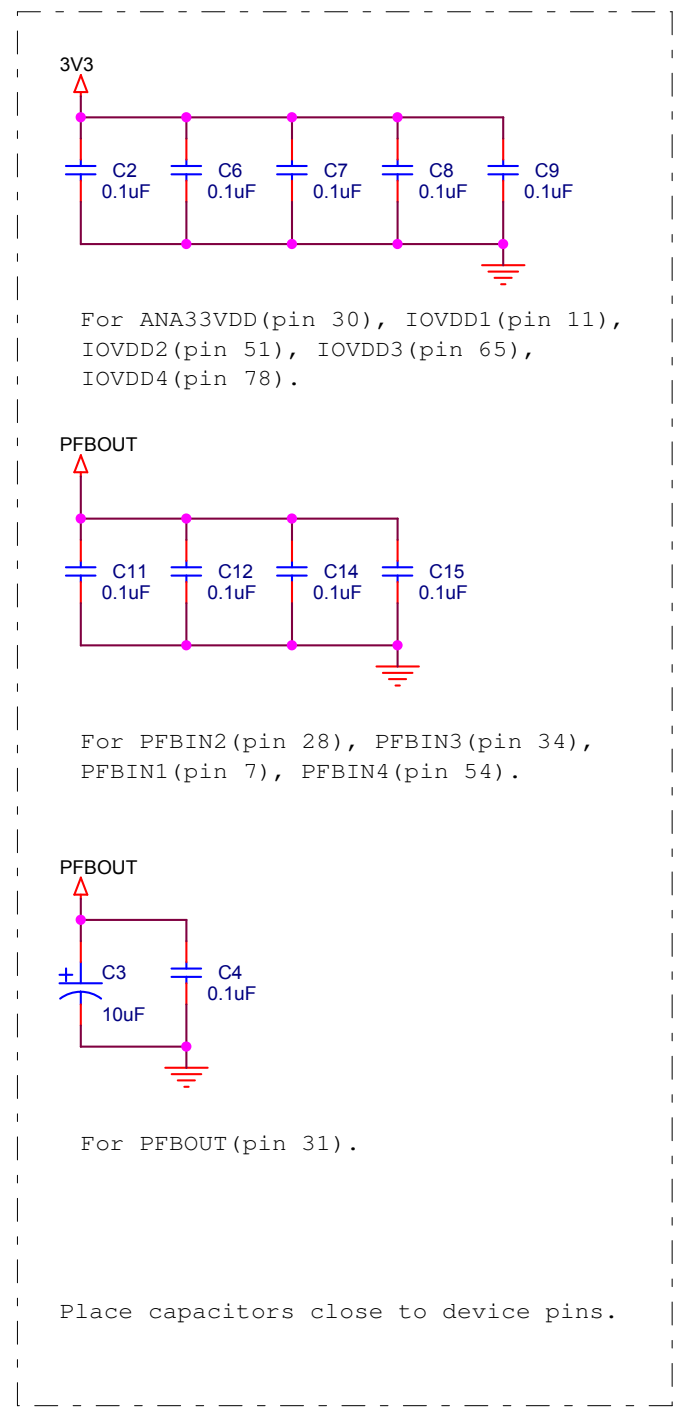
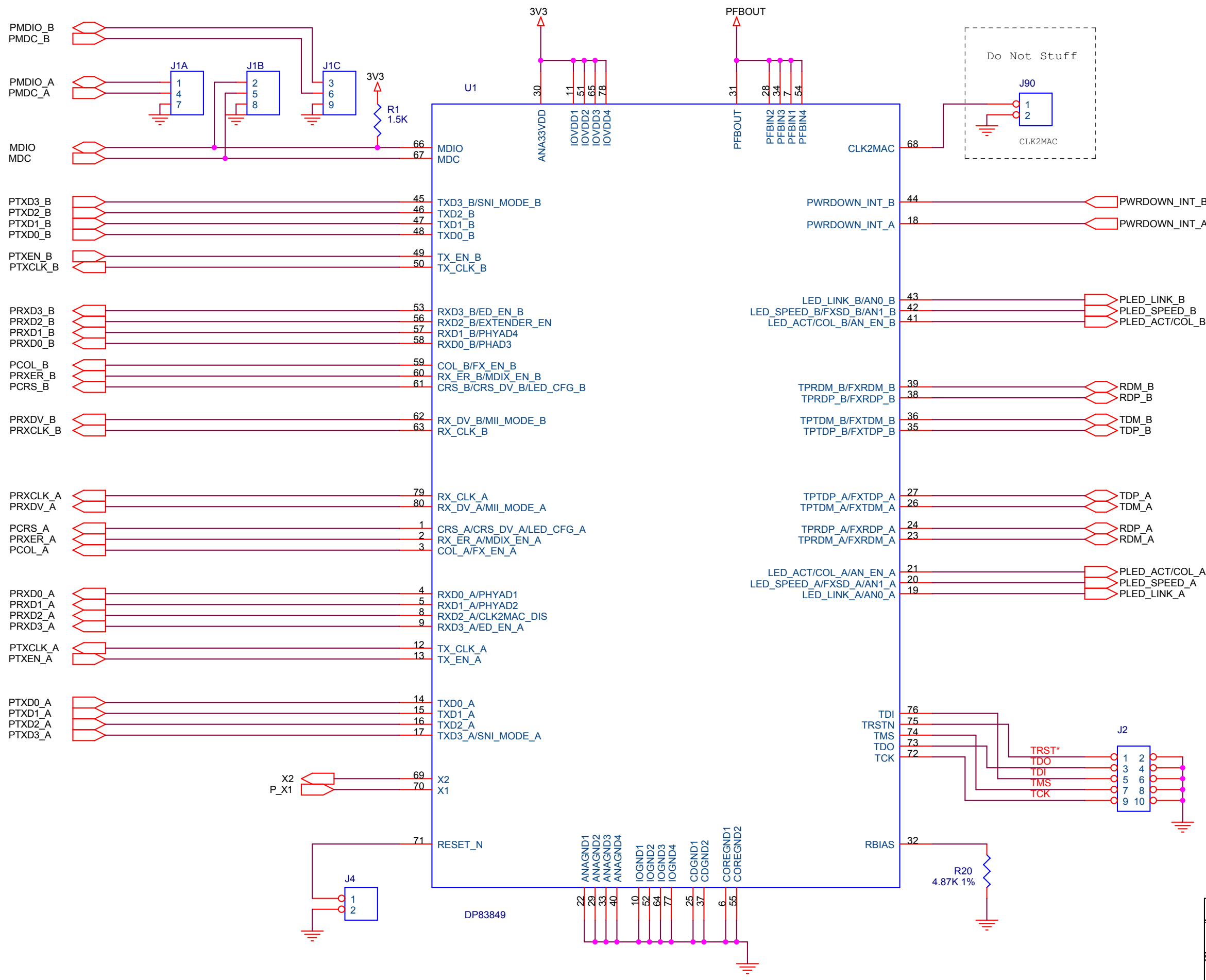
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Revisions note:

- Rev 1.0: Initial release.
- Rev 1.1:
  - Replaced D2, D3, D4, D5, D6, D7 with different LEDs
  - Removed D1 and R62
  - Changed R231 to 100 ohms



Title		
DP83849 DUAL PHYTER DEMO II (Stump Jumper) - Cover		
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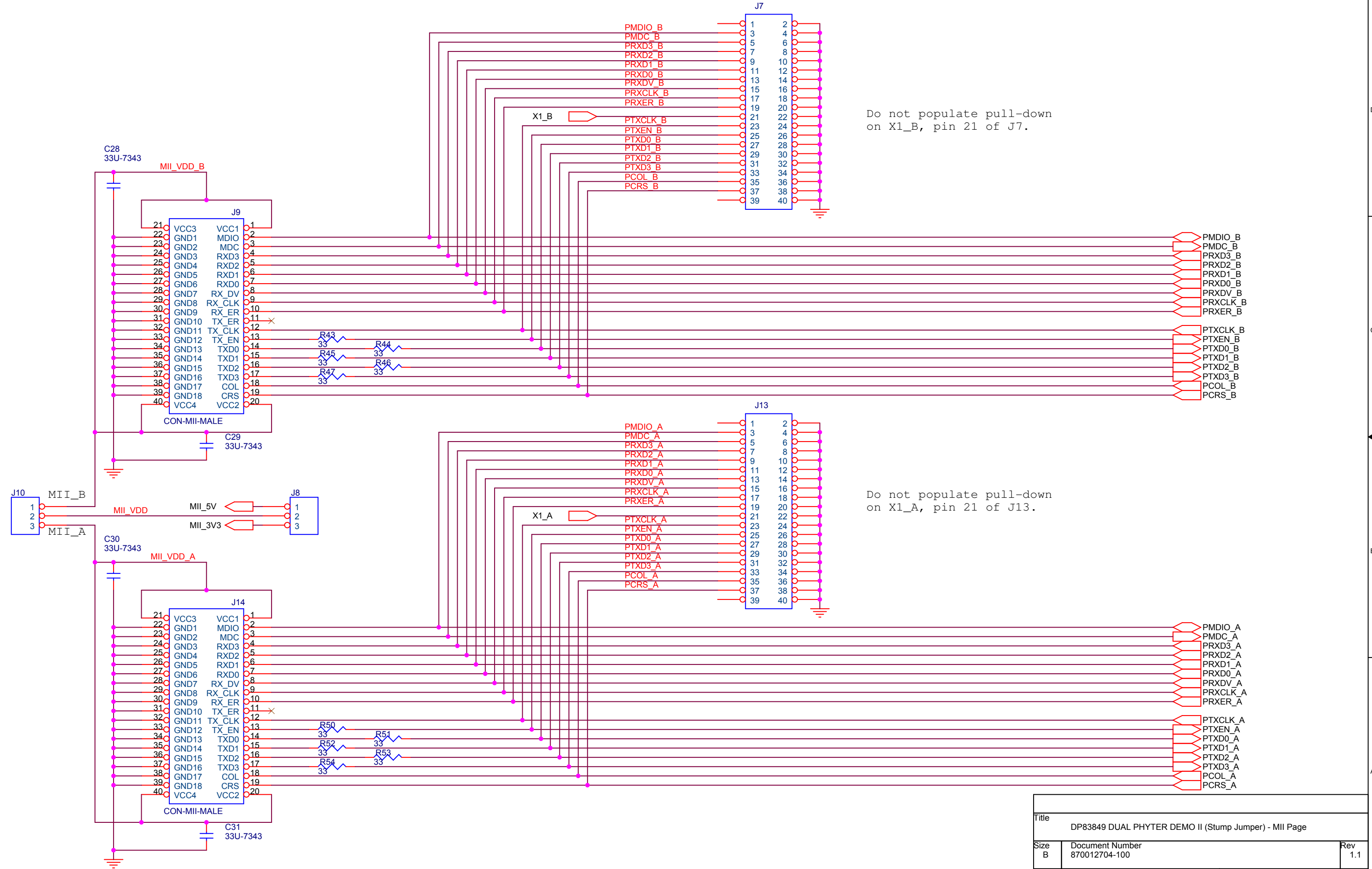
For ANA33VDD(pin 30), IOVDD1(pin 11), IOVDD2(pin 51), IOVDD3(pin 65), IOVDD4(pin 78).

For PFBIN2(pin 28), PFBIN3(pin 34), PFBIN1(pin 7), PFBIN4(pin 54).

For PFBOUT(pin 31).

Place capacitors close to device pins.

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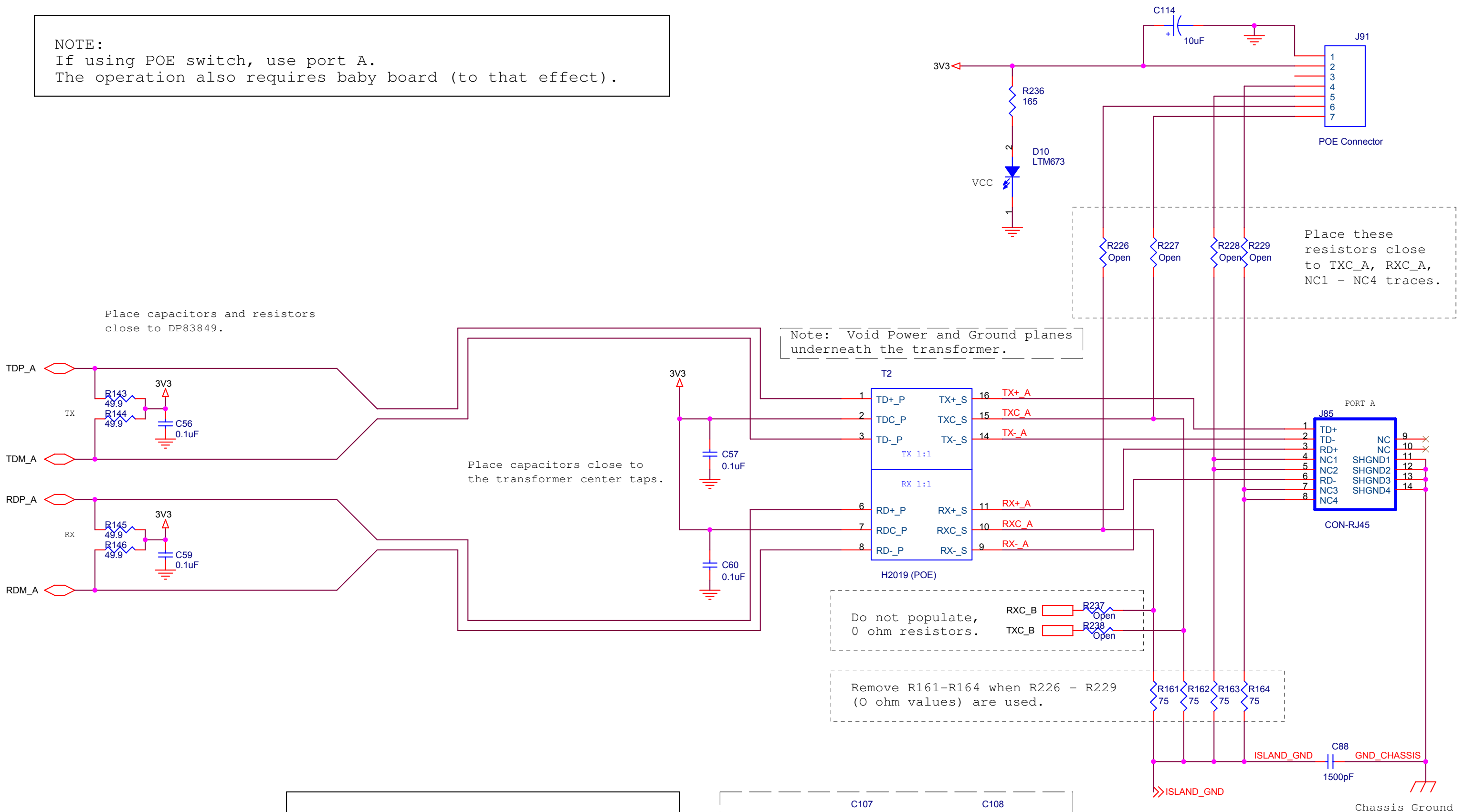


Do not populate pull-down on X1\_B, pin 21 of J7.

Do not populate pull-down on X1\_A, pin 21 of J13.

Title		
DP83849 DUAL PHYTER DEMO II (Stump Jumper) - MII Page		
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**NOTE:**  
 If using POE switch, use port A.  
 The operation also requires baby board (to that effect).



Place capacitors and resistors close to DP83849.

Note: Void Power and Ground planes underneath the transformer.

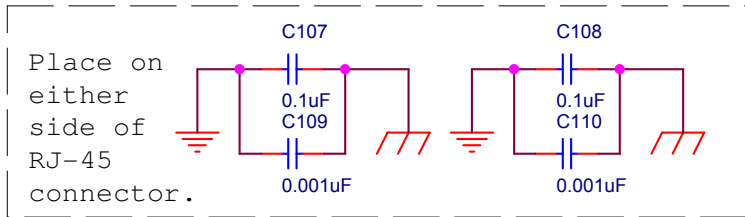
Place capacitors close to the transformer center taps.

Place these resistors close to TXC\_A, RXC\_A, NC1 - NC4 traces.

Do not populate, 0 ohm resistors.  
 RXC\_B R237 Open  
 TXC\_B R238 Open

Remove R161-R164 when R226 - R229 (0 ohm values) are used.

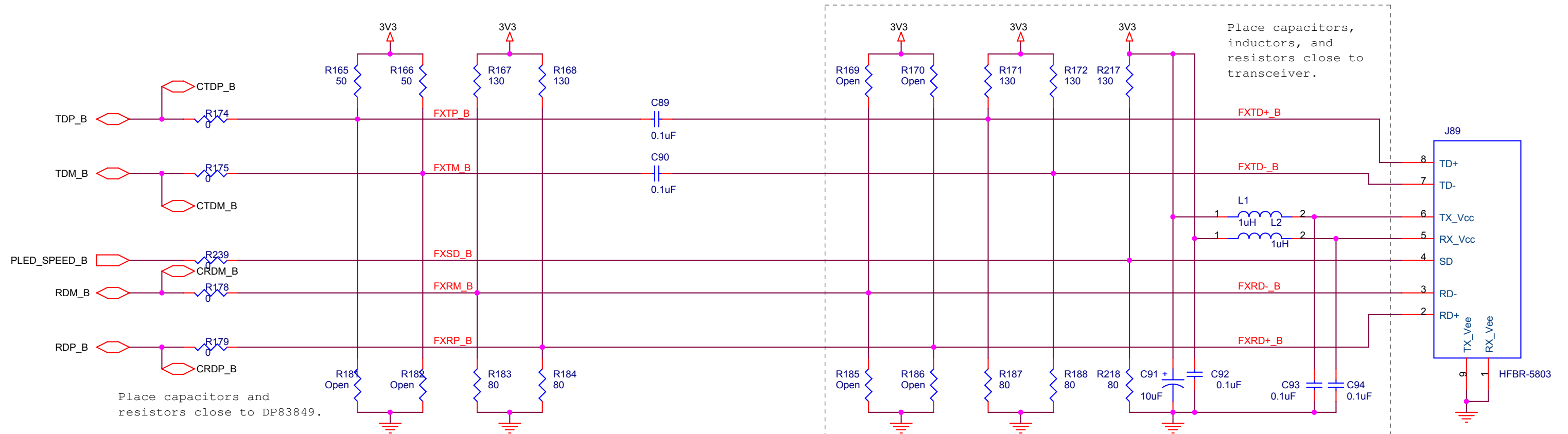
**For magnetic:**  
 - Use H1102 for normal application  
 - Use H2019 for POE application



Title		
DP83849 DUAL PHYTER DEMO II (Stump Jumper) - Port A TP Page		
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NOTE:

- For fiber operation, populate all items on this page.
- For copper operation, do not populate all items on this page.



Place capacitors and resistors close to DP83849.

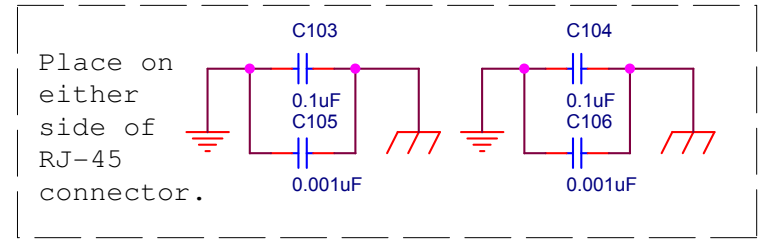
Important note:

- R174, R175, R178, R179, R239 are to be routed on bottom.

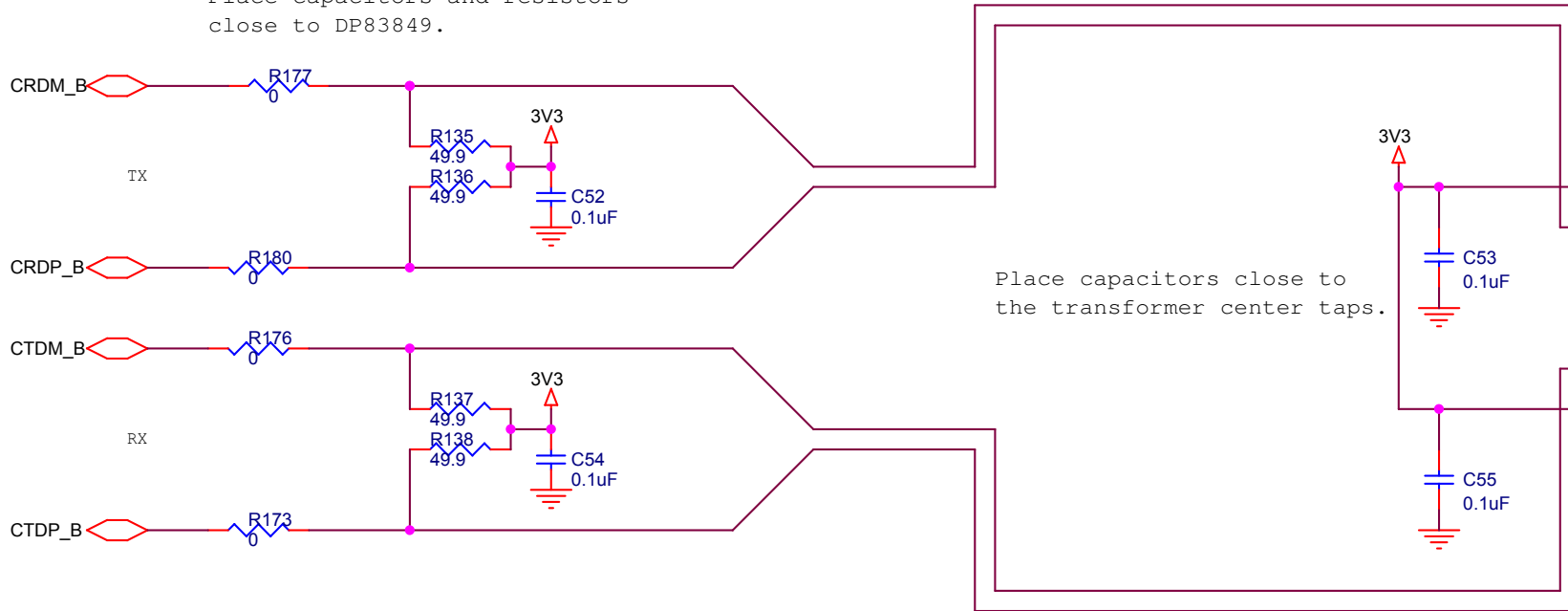
Title		
DP83849 DUAL PHYTER DEMO II (Stump Jumper) - Port B FX Page		
Size	Document Number	Rev
B	870012704-100	1.1
Date:	Thursday, December 15, 2005	Sheet 5 of 8

**NOTE:**

- For copper operation, populate all items on this page.
- For fiber operation, do not populate all items on this page.



Place capacitors and resistors close to DP83849.

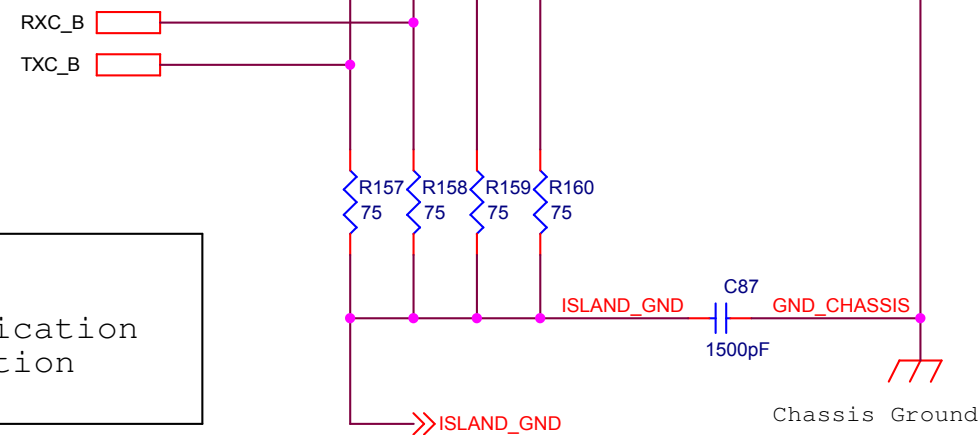


Place capacitors close to the transformer center taps.

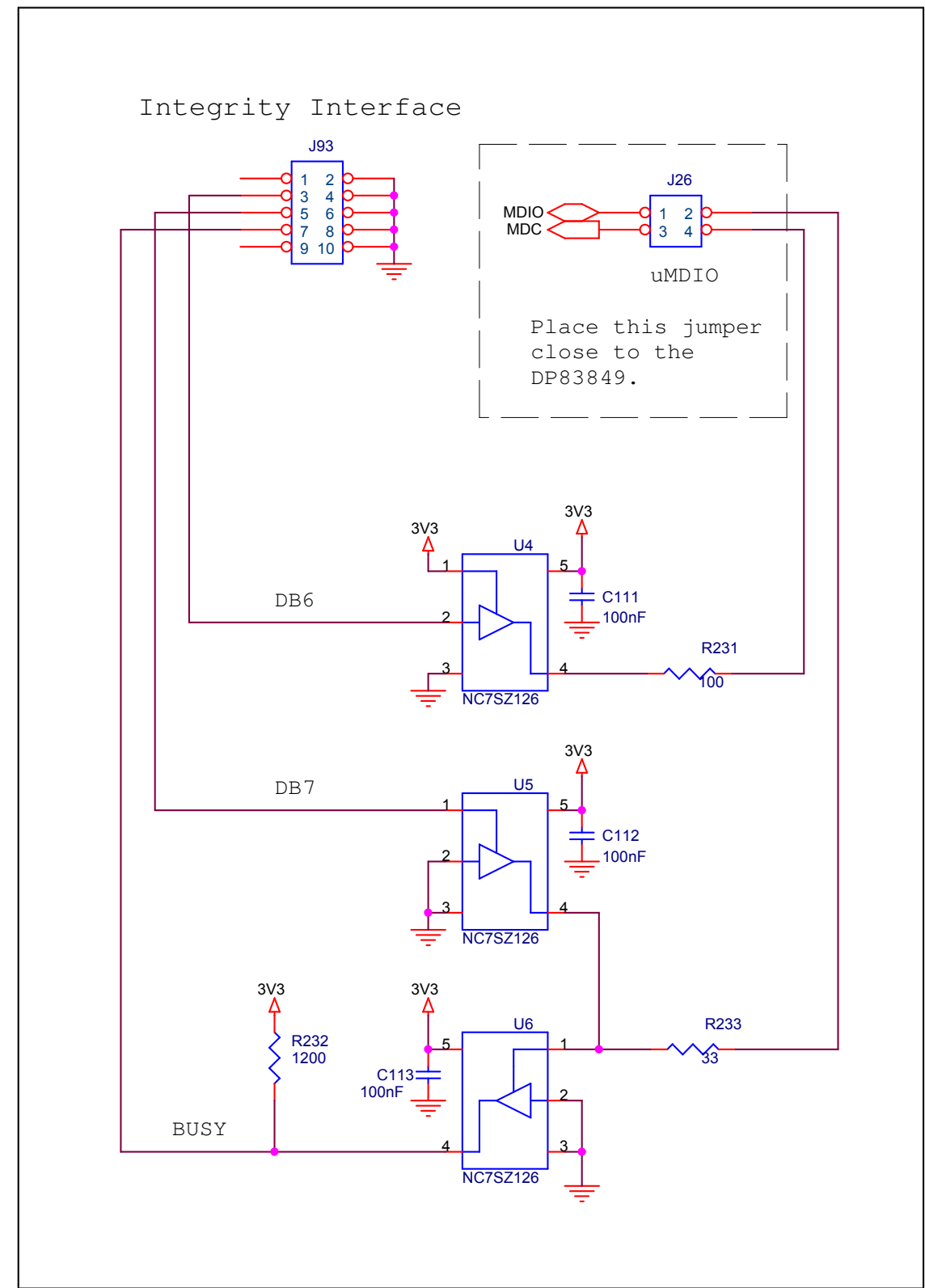
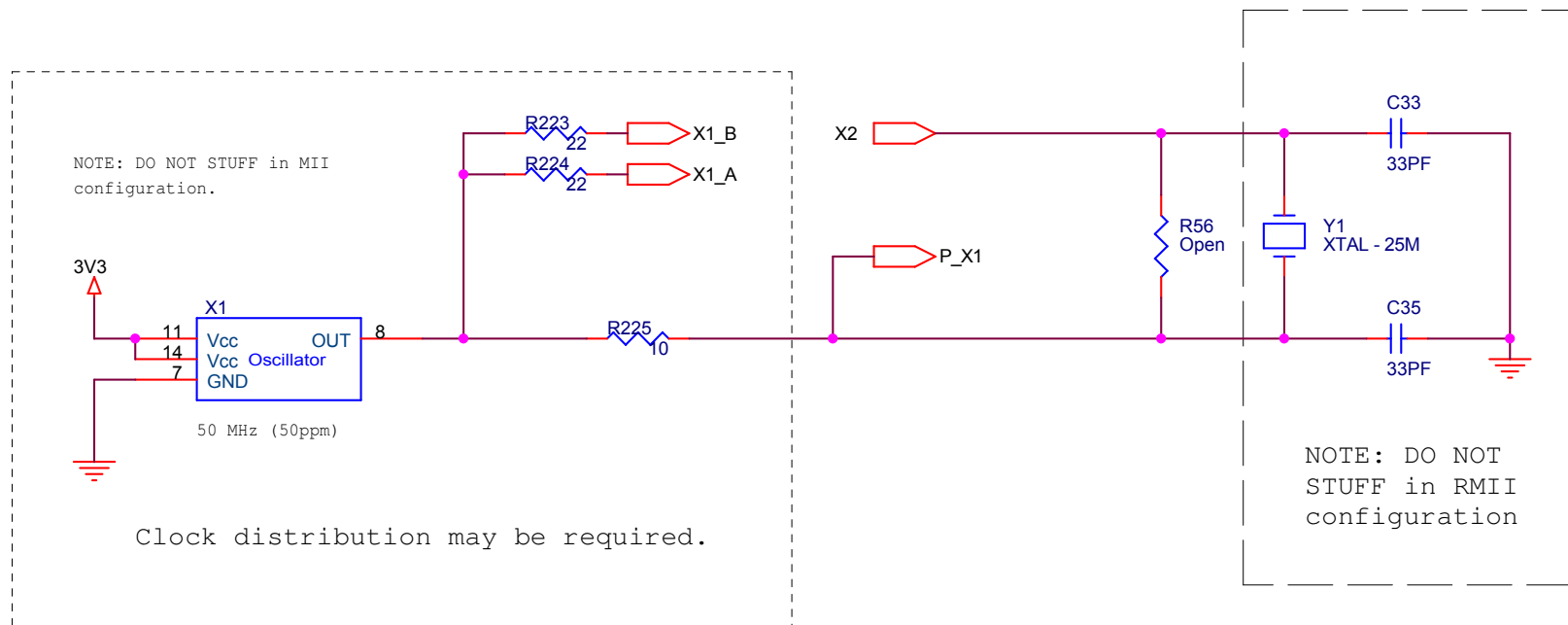
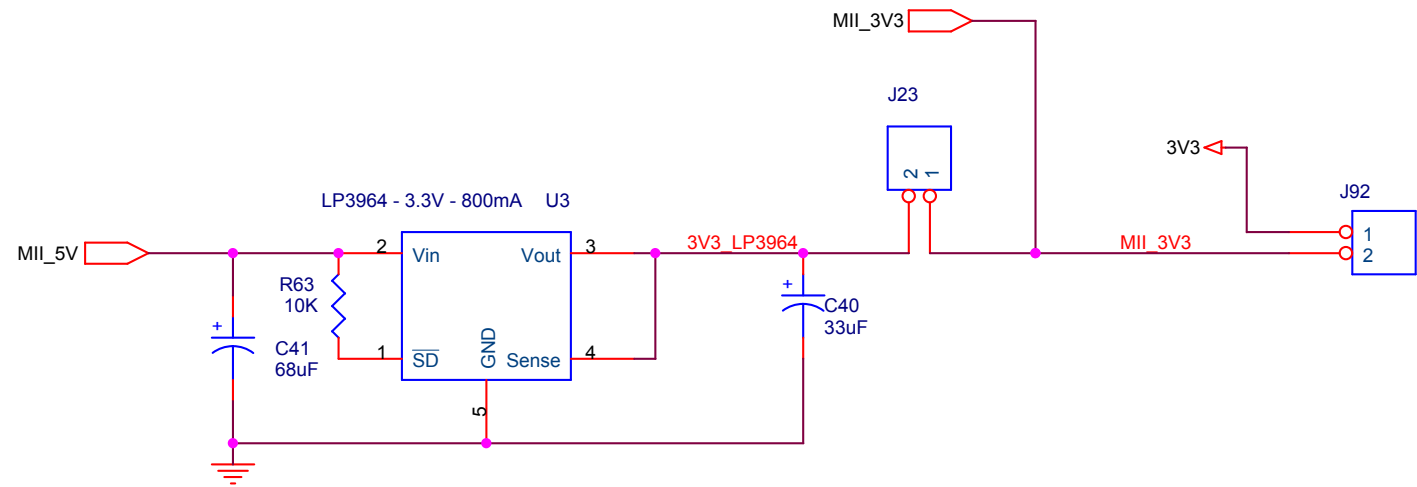
Note: Void Power and Ground planes underneath the transformer.

Important note:  
- R173, R176, R177, R180 are to be routed on top.

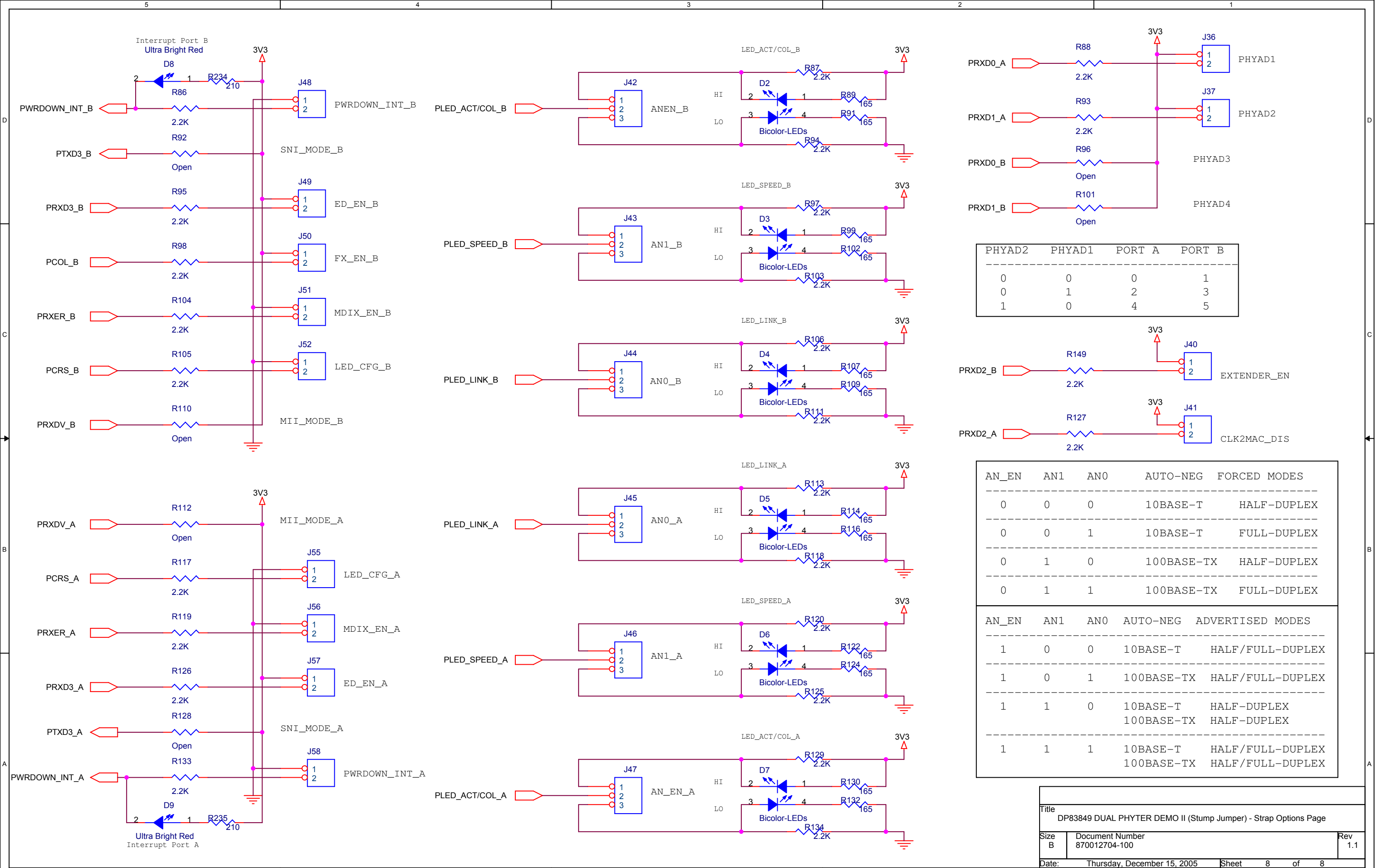
For magnetic:  
- Use H1102 for normal application  
- Use H2019 for POE application



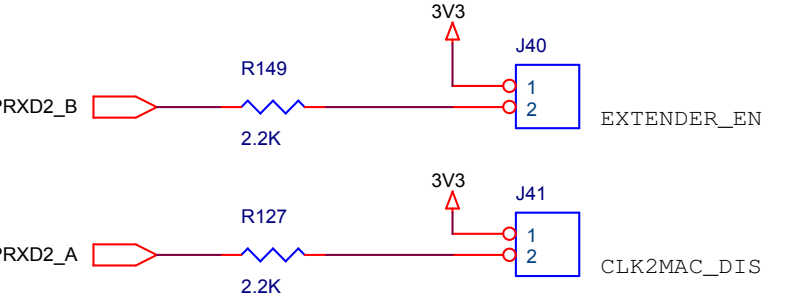
Title		
DP83849 DUAL PHYTER DEMO II (Stump Jumper) - Port B TP Page		
Size	Document Number	Rev
B	870012704-100	1.1
Date:	Thursday, December 15, 2005	Sheet 6 of 8



Title DP83849 DUAL PHYTER DEMO II (Stump Jumper) - Power, Clock, uMDIO Page		
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PHYAD2	PHYAD1	PORT A	PORT B
0	0	0	1
0	1	2	3
1	0	4	5



AN_EN	AN1	AN0	AUTO-NEG	FORCED MODES
0	0	0	10BASE-T	HALF-DUPLEX
0	0	1	10BASE-T	FULL-DUPLEX
0	1	0	100BASE-TX	HALF-DUPLEX
0	1	1	100BASE-TX	FULL-DUPLEX

AN_EN	AN1	AN0	AUTO-NEG	ADVERTISED MODES
1	0	0	10BASE-T	HALF/FULL-DUPLEX
1	0	1	100BASE-TX	HALF/FULL-DUPLEX
1	1	0	10BASE-T 100BASE-TX	HALF-DUPLEX HALF-DUPLEX
1	1	1	10BASE-T 100BASE-TX	HALF/FULL-DUPLEX HALF/FULL-DUPLEX



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